



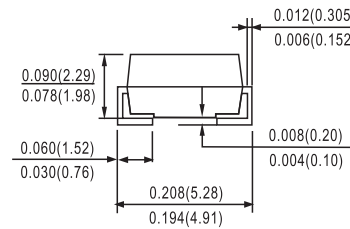
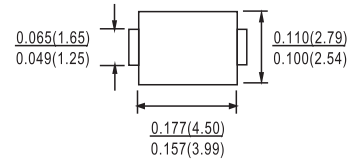
FEATURES

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.74 V Max @ 2.0 A, T_J = 150°C)
- Pb-Free Packages are Available

MECHANICAL DATA

- Case: Epoxy, Molded
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Protection: Human Body Model > 4000 V (Class 3)
Machine Model > 400 V (Class C)

DO-214AC(SMA)



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	150 200	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
Average Rectified Forward Current @ T _L = 155°C @ T _L = 135°C	I _{F(AV)}	1.0 2.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	40	A
Operating Junction Temperature Range	T _J	-65 to +175	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Lead (T _L = 25°C) (Note 1)	Ψ _{siJL} (Note 2)	24	°C/W
Thermal Resistance, Junction to Ambient (Note 1)	R _{θJA}	216	

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 3) (i _F = 2.0 A, T _J = 25°C) (i _F = 2.0 A, T _J = 150°C)	v _F	0.95 0.77	Volts
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, T _J = 25°C) (Rated dc Voltage, T _J = 150°C)	i _R	2.0 50	μA
Maximum Reverse Recovery Time (i _F = 1.0 A, di/dt = 50 A/μs)	t _{rr}	35	ns

1. Rating applies when surface mounted on the minimum pad size recommended, PC Board FR-4.
 2. In compliance with JEDEC 51, these values (historically represented by R_{θJL}) are now referenced as Ψ_{siJL}.
 3. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.



RATINGS AND CHARACTERISTIC CURVES

MURA215T3, MURA220T3

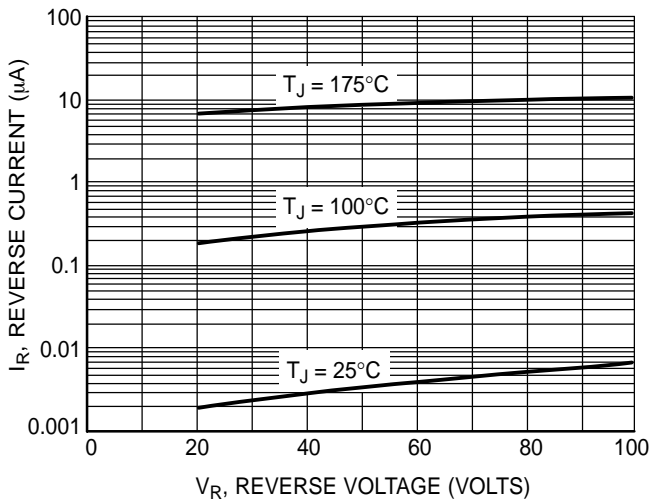


Figure 1. Typical Reverse Current

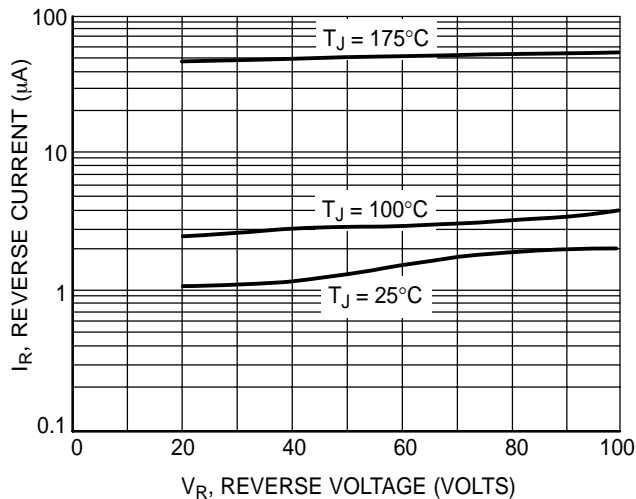


Figure 2. Maximum Reverse Current

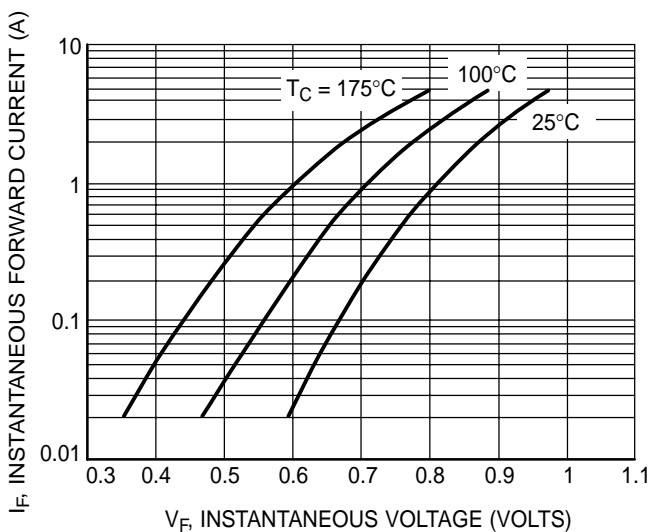


Figure 3. Typical Forward Voltage

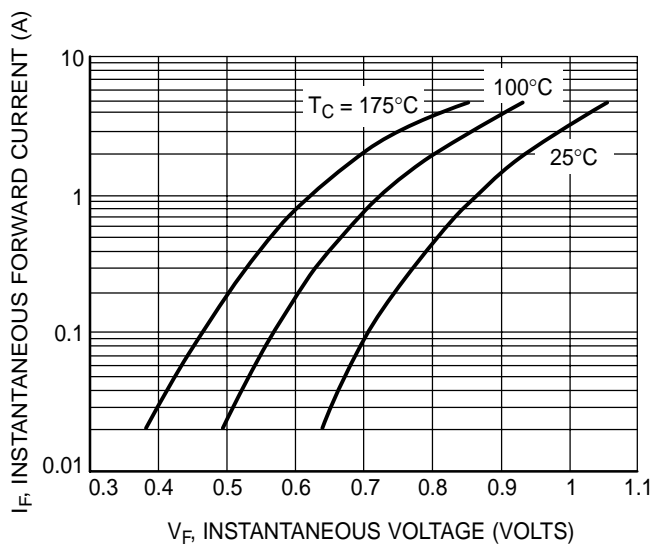


Figure 4. Maximum Forward Voltage

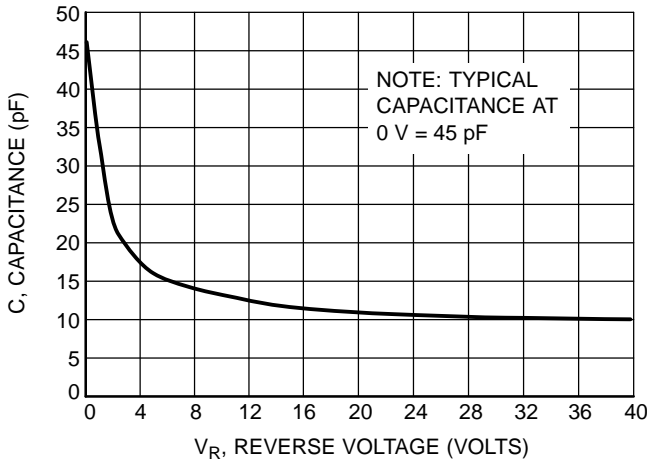


Figure 5. Typical Capacitance

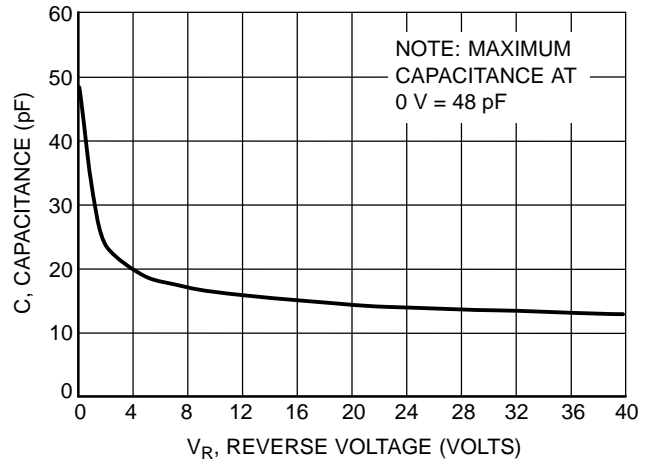


Figure 6. Maximum Capacitance

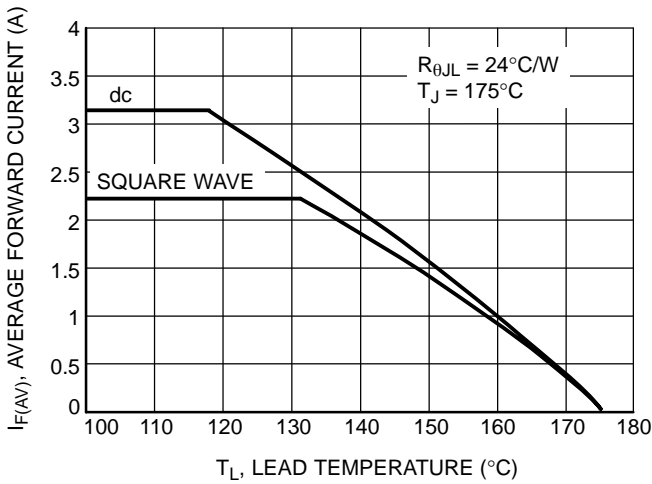


Figure 7. Current Derating, Lead

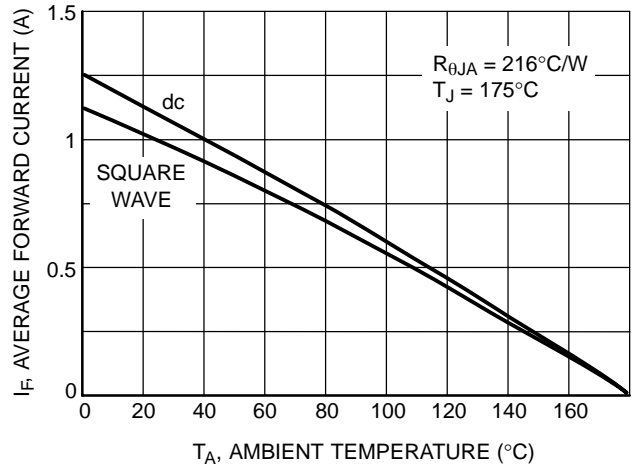


Figure 8. Current Derating, Ambient (FR-4 Board with Minimum Pad)

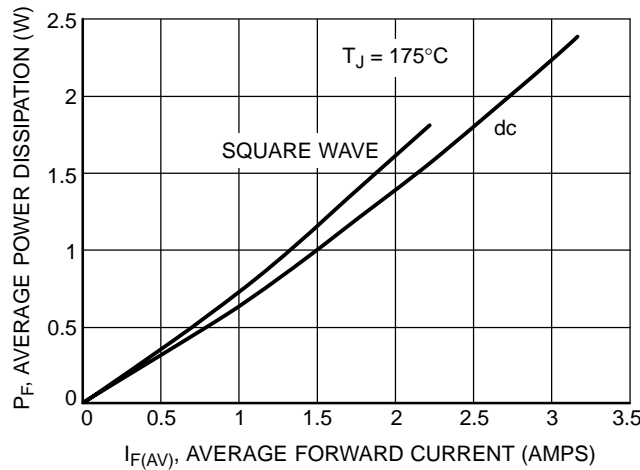


Figure 9. Power Dissipation